# DATA BOOK
# PACKAGE OUTLINE

| LEADFRAME EXAMPLE |
| --- |
| 4218497 |

| | | | |
| --- | --- | --- | --- |
| DRAFTER: | T. LEQUANG | DATE: | 10/08/2013 |
| DESIGNER: | | DATE: | |
| CHECKER: | K. SINCERBOX & V. PAKU | DATE: | 01/05/2017 |
| ENGINEER: | B. TAN | DATE: | 01/26/2017 |
| APPROVED: | E. REY & D. CHIN | DATE: | 01/26/2017 |
| RELEASED: | WDM | DATE: | 01/27/2017 |
| TEMPLATE INFO: | EDGE# 4218519 | DATE: | 04/07/2016 |

DIMENSIONS IN MILLIMETERS

TEXAS INSTRUMENTS
SEMICONDUCTOR OPERATIONS

CODE IDENTITY NUMBER 01295

ePOD, RGH0016A / WQFN,
16 PIN, 0.5 MM PITCH

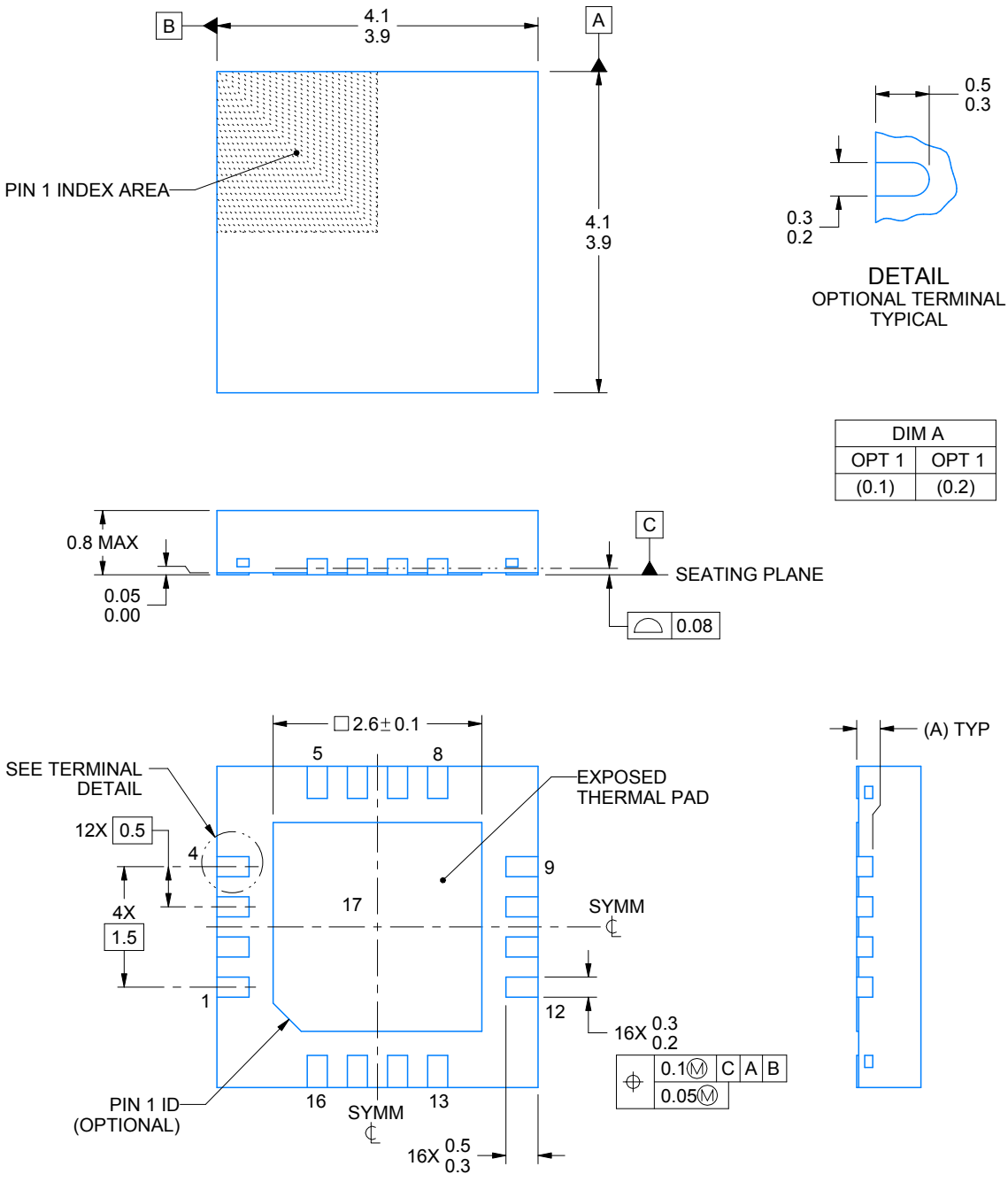
| SCALE | SIZE | | REV | PAGE |
| --- | --- | --- | --- | --- |
| NTS | A | 4214978 | B | 1 OF 5 |

# RGH0016A

# PACKAGE OUTLINE

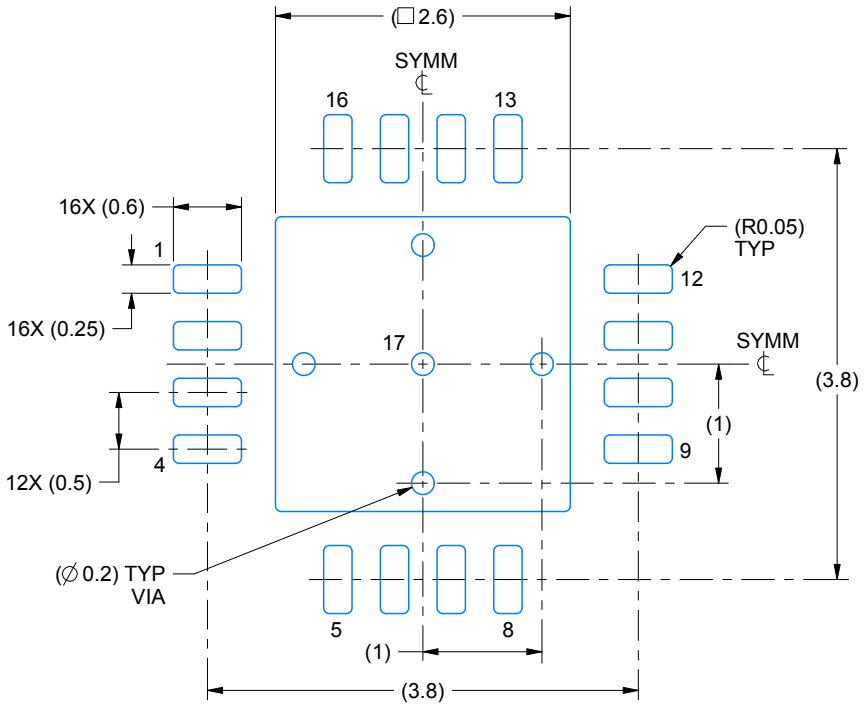
## WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

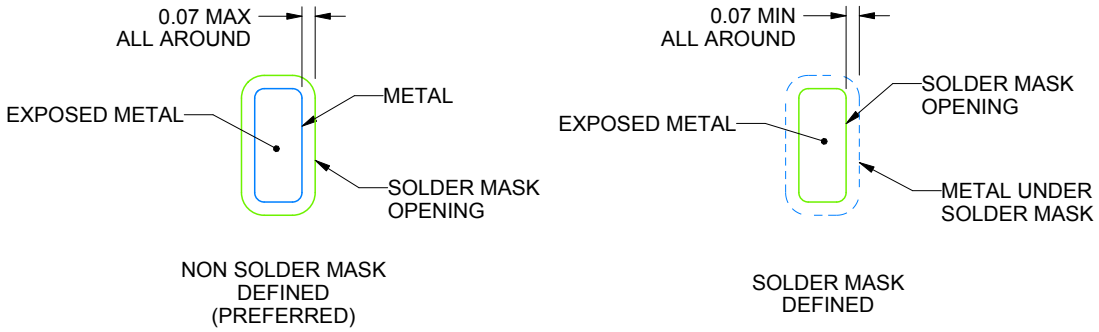



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X




SOLDER MASK DETAILS

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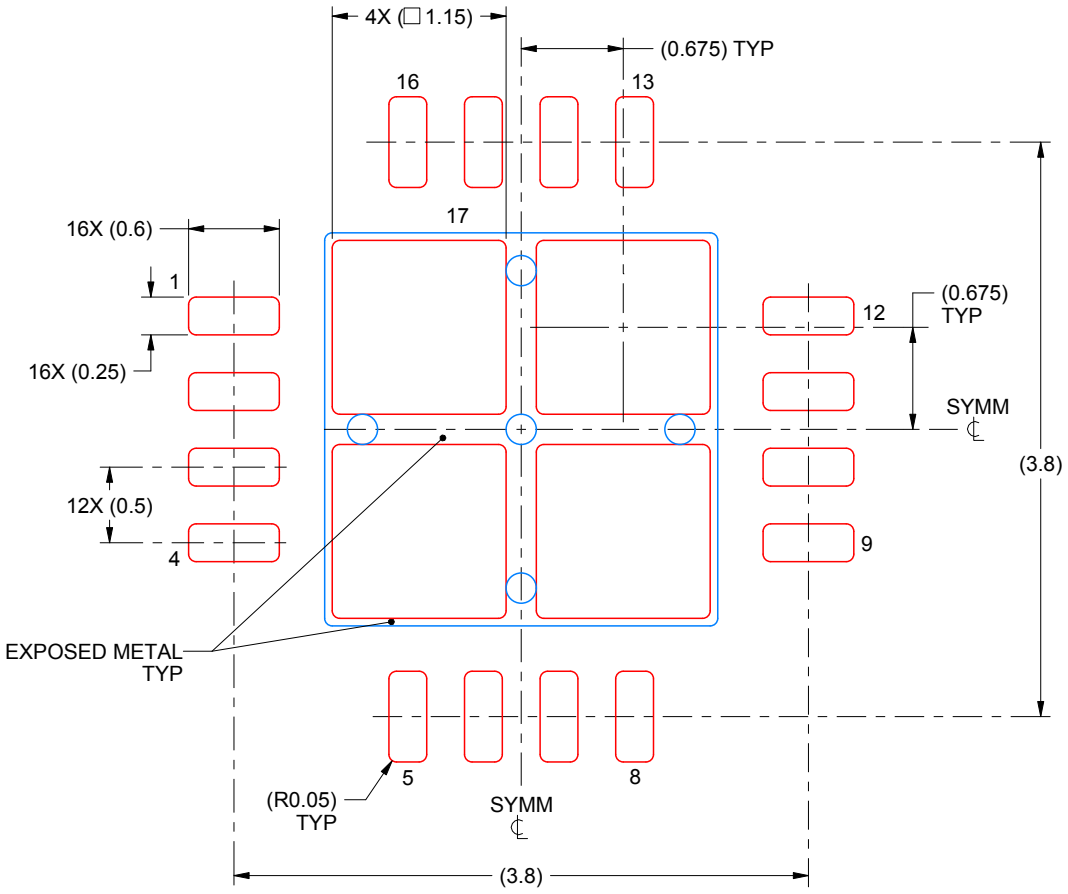
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 17
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## REVISIONS

| REV | DESCRIPTION | ECR | DATE | ENGINEER / DRAFTER |
|---|---|---|---|---|
| A | RELEASE NEW DRAWING | 2132285 | 09/16/2013 | C. MANACK / T. LEQUANG |
| B | ADD STAND-OFF & COPLANARITY; UPDATE PER CURRENT STANDARDS | 2161107 | 01/27/2017 | B. TAN / T. LEQUANG |